ABSTRACT

A semiconductor wafer is taken as an object to be irradiated, to which a protection sheet S is stuck via an ultraviolet cured adhesive layer, and an ultraviolet irradiation part 12 is disposed facing the protection sheet S, the ultraviolet irradiation part 12 being provided with a plurality of the ultraviolet light-emitting diodes 21 disposed on the substrate 20. The light-emitting diodes 21 are arranged to be spaced equally from each other on the straight lines L1 of plural rows substantially perpendicular to a relative movement direction to the wafer, and between the neighboring light-emitting diodes in each row, a part of the light-emitting diode of the neighboring row is positioned.